

# Global Ultra-thin Copper Foil for IC Packaging Market Growth 2024-2030

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## Abstracts

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IC substrate is mainly used to package IC chips. Its thickness and weight directly affect the thinness and thinness of IC packaging products. As the functions of IC components tend to become more complex, the number of layers used also increases, and the thickness and weight of PCBs also increase. In order to meet the demand for thinner and lighter terminal electronic products, ultra-thin copper foil will become a trend in PCB manufacturing.

Ultra-thin copper foil is mainly used for IC packaging substrates in semiconductor/IC packaging. Under normal circumstances, the thickness of ultra-thin copper foil for IC carrier boards is generally between 2um and 5um.

The global Ultra-thin Copper Foil for IC Packaging market size is projected to grow from US\$ 1204 million in 2024 to US\$ 1845 million in 2030; it is expected to grow at a CAGR of 7.4% from 2024 to 2030.

LP Information, Inc. (LPI) ' newest research report, the "Ultra-thin Copper Foil for IC Packaging Industry Forecast" looks at past sales and reviews total world Ultra-thin Copper Foil for IC Packaging sales in 2023, providing a comprehensive analysis by region and market sector of projected Ultra-thin Copper Foil for IC Packaging sales for 2024 through 2030. With Ultra-thin Copper Foil for IC Packaging sales broken down by region, market sector and sub-sector, this report provides a detailed analysis in US\$ millions of the world Ultra-thin Copper Foil for IC Packaging industry.

This Insight Report provides a comprehensive analysis of the global Ultra-thin Copper

Foil for IC Packaging landscape and highlights key trends related to product segmentation, company formation, revenue, and market share, latest development, and M&A activity. This report also analyzes the strategies of leading global companies with a focus on Ultra-thin Copper Foil for IC Packaging portfolios and capabilities, market entry strategies, market positions, and geographic footprints, to better understand these firms' unique position in an accelerating global Ultra-thin Copper Foil for IC Packaging market.

This Insight Report evaluates the key market trends, drivers, and affecting factors shaping the global outlook for Ultra-thin Copper Foil for IC Packaging and breaks down the forecast by Type, by Application, geography, and market size to highlight emerging pockets of opportunity. With a transparent methodology based on hundreds of bottom-up qualitative and quantitative market inputs, this study forecast offers a highly nuanced view of the current state and future trajectory in the global Ultra-thin Copper Foil for IC Packaging.

United States market for Ultra-thin Copper Foil for IC Packaging is estimated to increase from US\$ million in 2023 to US\$ million by 2030, at a CAGR of % from 2024 through 2030.

China market for Ultra-thin Copper Foil for IC Packaging is estimated to increase from US\$ million in 2023 to US\$ million by 2030, at a CAGR of % from 2024 through 2030.

Europe market for Ultra-thin Copper Foil for IC Packaging is estimated to increase from US\$ million in 2023 to US\$ million by 2030, at a CAGR of % from 2024 through 2030.

Global key Ultra-thin Copper Foil for IC Packaging players cover SK Nexilis, Mitsui Mining & Smelting, ILJIN Materials, Industrie De Nora, Fukuda Metal Foil & Powder, etc. In terms of revenue, the global two largest companies occupied for a share nearly % in 2023.

This report presents a comprehensive overview, market shares, and growth opportunities of Ultra-thin Copper Foil for IC Packaging market by product type, application, key manufacturers and key regions and countries.

Segmentation by Type:

2?m

3?m

4?m

5?m

Segmentation by Application:

BGA

CSP

Others

This report also splits the market by region:

Americas

United States

Canada

Mexico

Brazil

APAC

China

Japan

Korea

Southeast Asia

India

Australia

Europe

Germany

France

UK

Italy

Russia

Middle East & Africa

Egypt

South Africa

Israel

Turkey

GCC Countries

The below companies that are profiled have been selected based on inputs gathered from primary experts and analysing the company's coverage, product portfolio, its market penetration.

SK Nexilis

Mitsui Mining & Smelting

ILJIN Materials

Industrie De Nora

Fukuda Metal Foil & Powder

Nippon Denkai

Carl Schlenk

UACJ Foil Corporation

Solus Advanced Materials

Nan Ya Plastics

Chaohua Technology

Guangdong Jia Yuan Tech

Nuode

TOP Nanometal Corporation

Shanghai Legion Compound Material

Guangzhou Fangbang Electronics

## Key Questions Addressed in this Report

What is the 10-year outlook for the global Ultra-thin Copper Foil for IC Packaging market?

What factors are driving Ultra-thin Copper Foil for IC Packaging market growth, globally and by region?

Which technologies are poised for the fastest growth by market and region?

How do Ultra-thin Copper Foil for IC Packaging market opportunities vary by end market size?

How does Ultra-thin Copper Foil for IC Packaging break out by Type, by Application?

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